



Microfluidic cell cooling system for electronics

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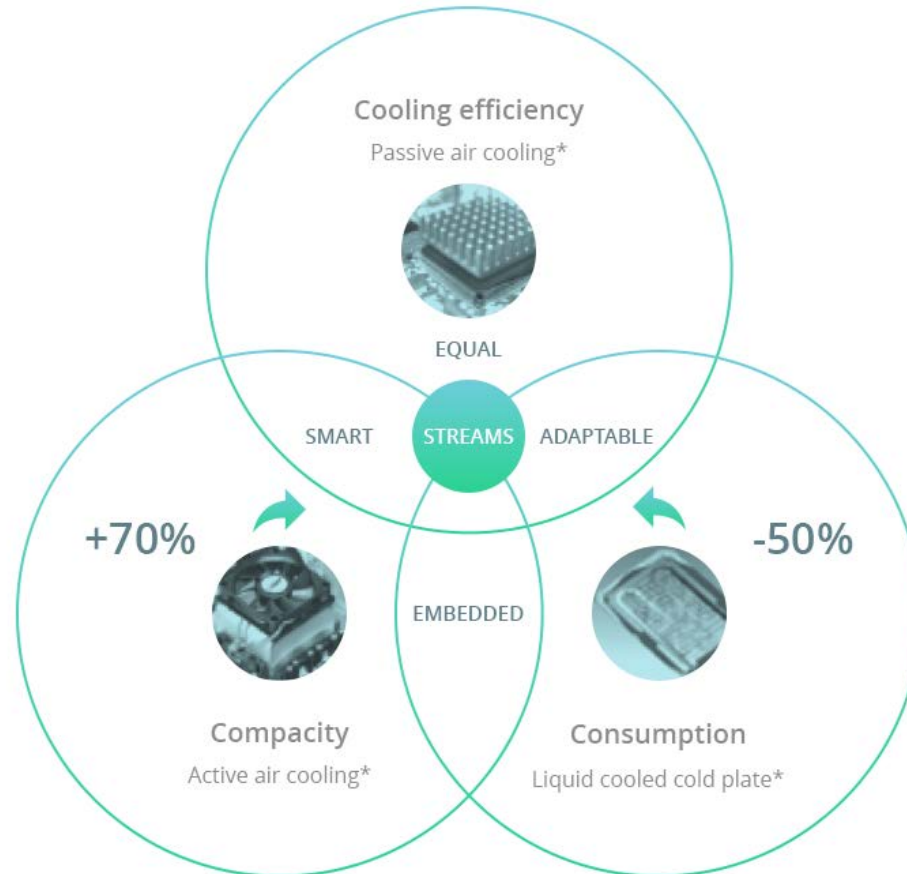
STREAMS

Smart Technologies for eneRgy Efficient Active
cooling in Advanced Microelectronic Systems



STREAMS Project

Smart Technologies for energy Efficient Active cooling in Advanced Microelectronic Systems



* Low points of state-of-the-art thermal management solutions

Consortium:





Thermal viability on advanced ICs

Liquid cooling based on microchannels

- Low thermal resistance coefficients.
- Large pressure drop (high pumping powers).
- Poor temperature uniformity.

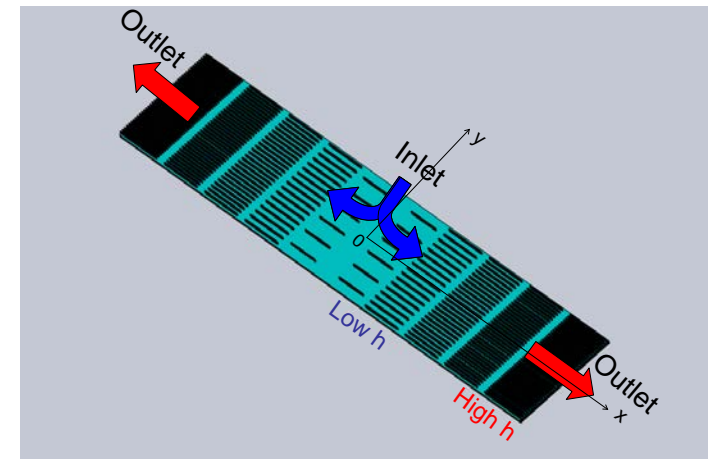


Hybrid jet impingement / microchannel

High temperature uniformity

Less pressure drop

Not a “universal solution”



[1] Flow rate: $1,6 \cdot 10^{-5} \text{ m}^3/\text{s}$, heat flux: $50 \text{ W}/\text{cm}^2$, standard deviation σ_T : $\approx 0,8 \text{ }^\circ\text{C}$.

[1] S. Riera, J. Barrau, M. Omri, L.G. Fr chet, J. Rosell, “Stepwise varying width microchannel cooling device for uniform wall temperature: experimental and numerical study”, Applied Thermal Engineering, Volume 78, Pages 30-38, 2015.



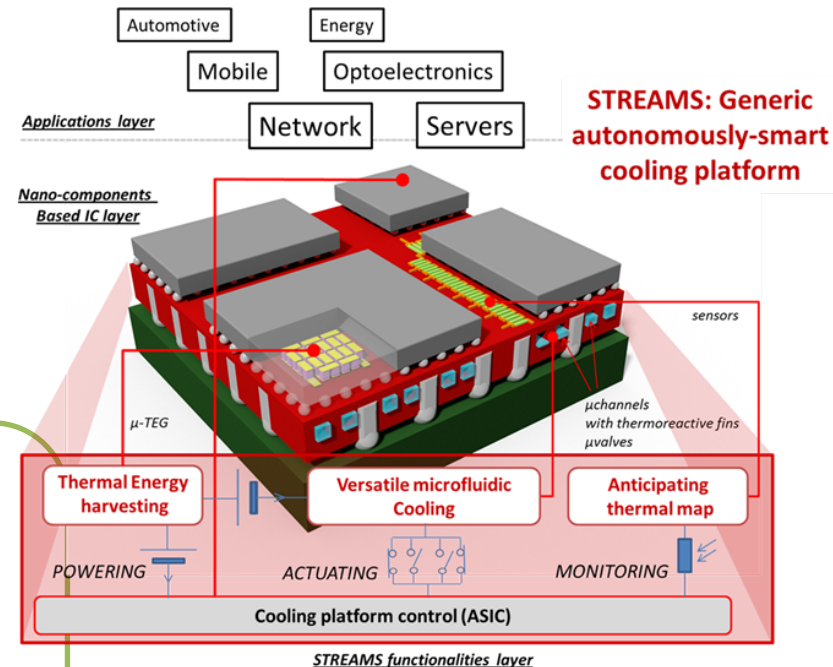
Proposal approach

Cooling device formed by a **matrix of microfluidic cells** with individual variable coolant flow rate.

Main objective of the project:

Avoid overcooling

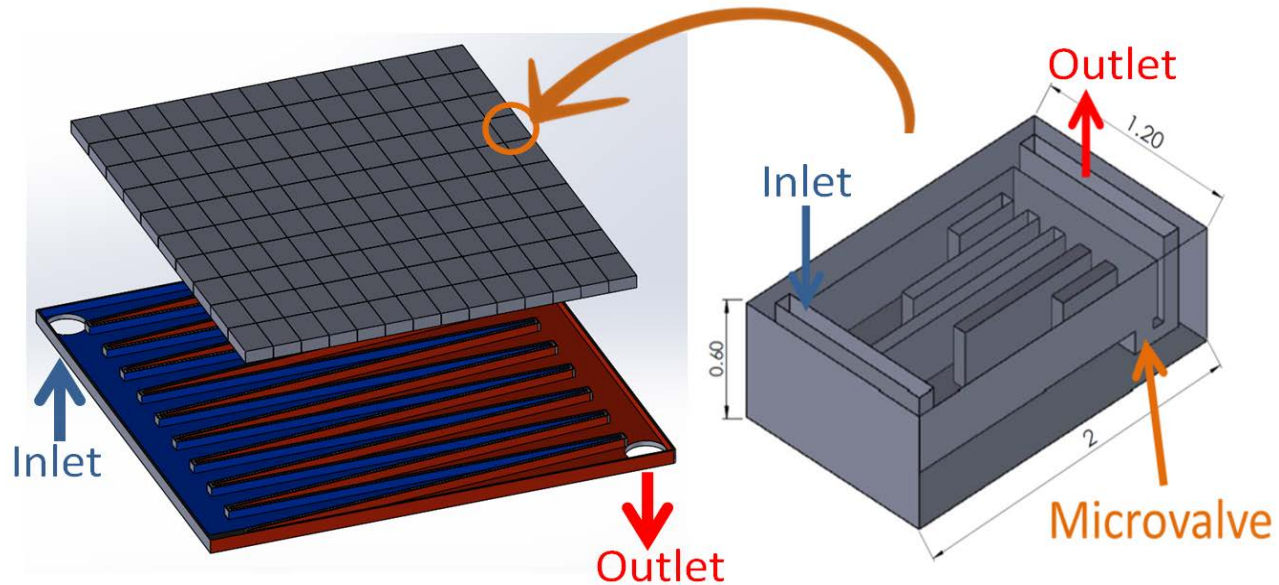
(By tailoring the distribution of the local heat extraction capacity to time dependent and non-uniform heat flux distributions)





Description of the thermal device

Matrix of microfluidic cells with distributor



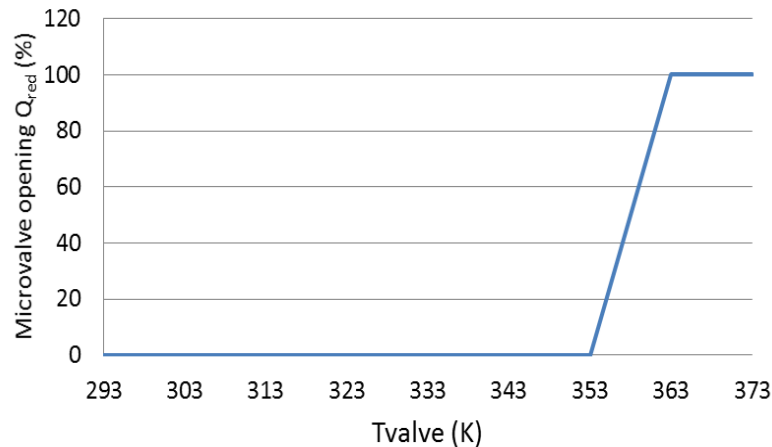
- Reduce the length of the coolant flow path (reduce ΔP).
- Locally control the flow rate in each cell through self-regulated microvalves.
- Microfluidic cell designed for optimum heat transfer while achieving good temperature uniformity.



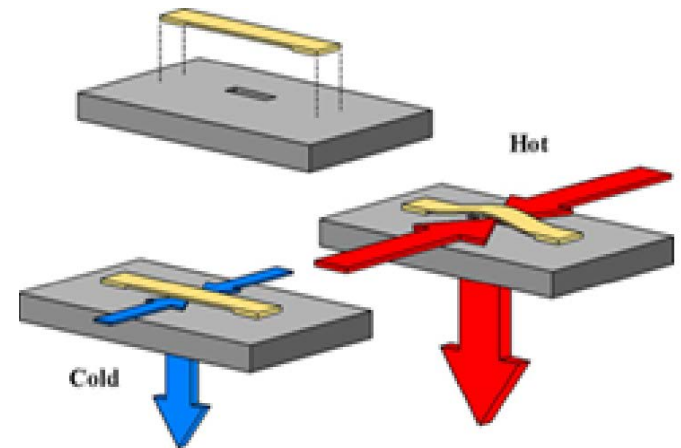
Thermal microvalves

Self adaptive microvalve: their aperture depends on their own temperature. [2]

Opening function of the microvalve



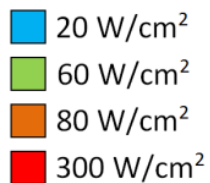
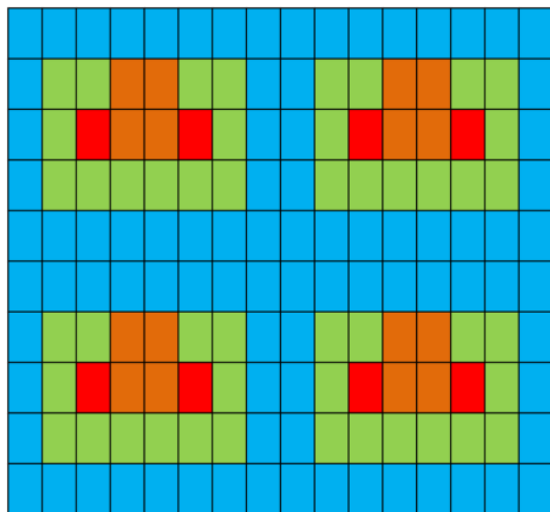
Placement of the hot and cold positions



- [2] M. McCarthy, N. Tiliakos, V. Modi, L.G. Fréchette, "Temperature-regulated nonlinear microvalves for self-adaptive MEMS cooling". Journal of Microelectromechanical Systems, Volume 17, Pages 998–1009, 2008.



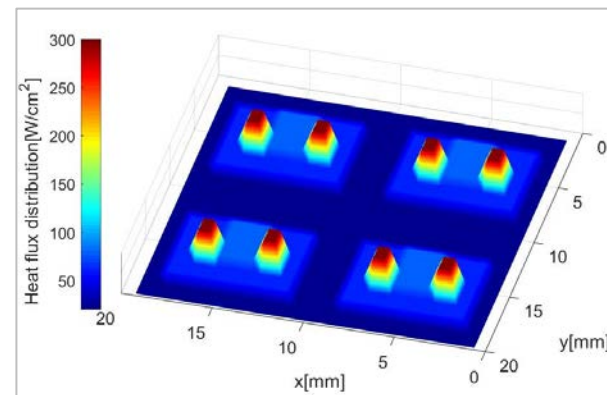
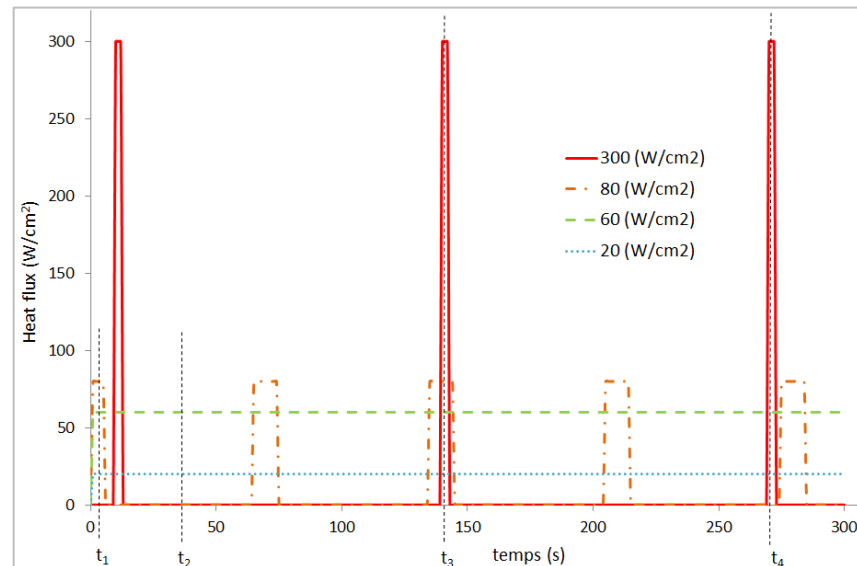
Heat load scenario



Matrix of 16x10 microfluidic cells.

- Inlet temperature: 50°C (worst condition)
- Maximum temperature on the chip surface < 100°C (design condition)

Time dependence of the heat loads



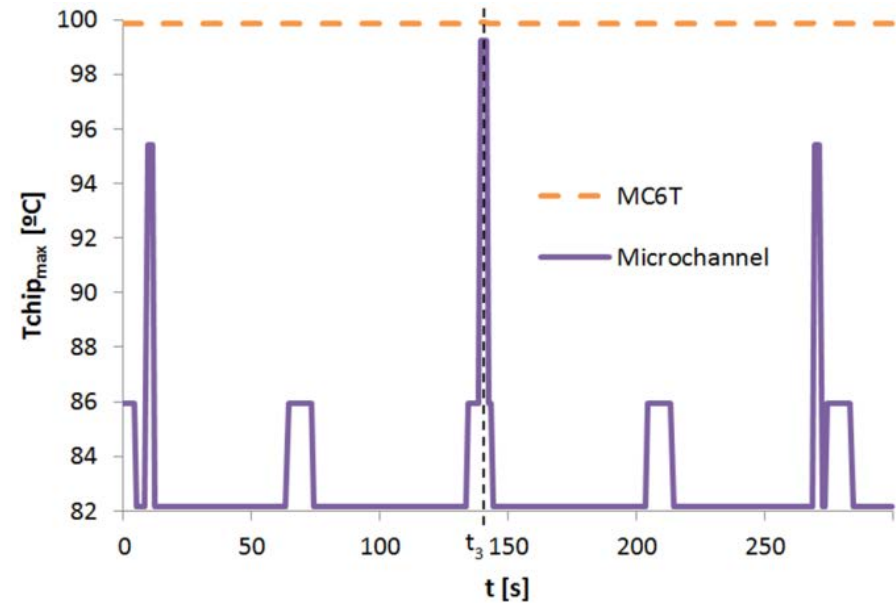
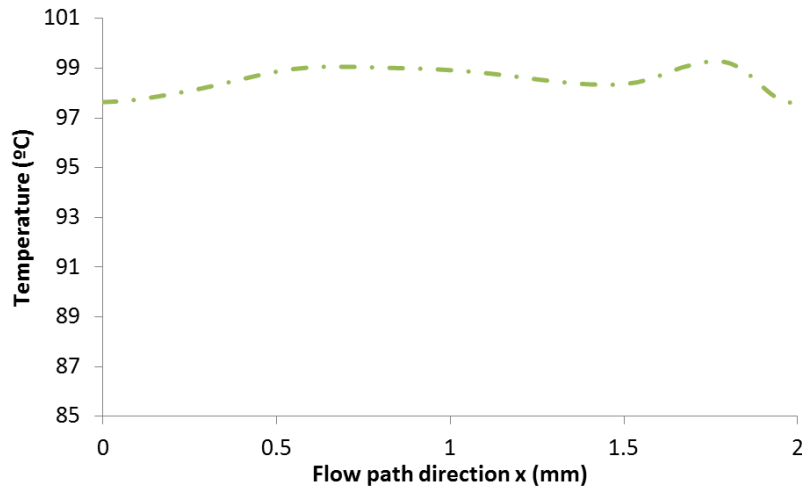
Heat flux distribution for t_3



Temperature uniformity over time

Objective of this study

Thermo-hydraulic performance of the microfluidic cells matrix under non-uniform and time dependent heat load scenario.



Chip maximum temperature over time

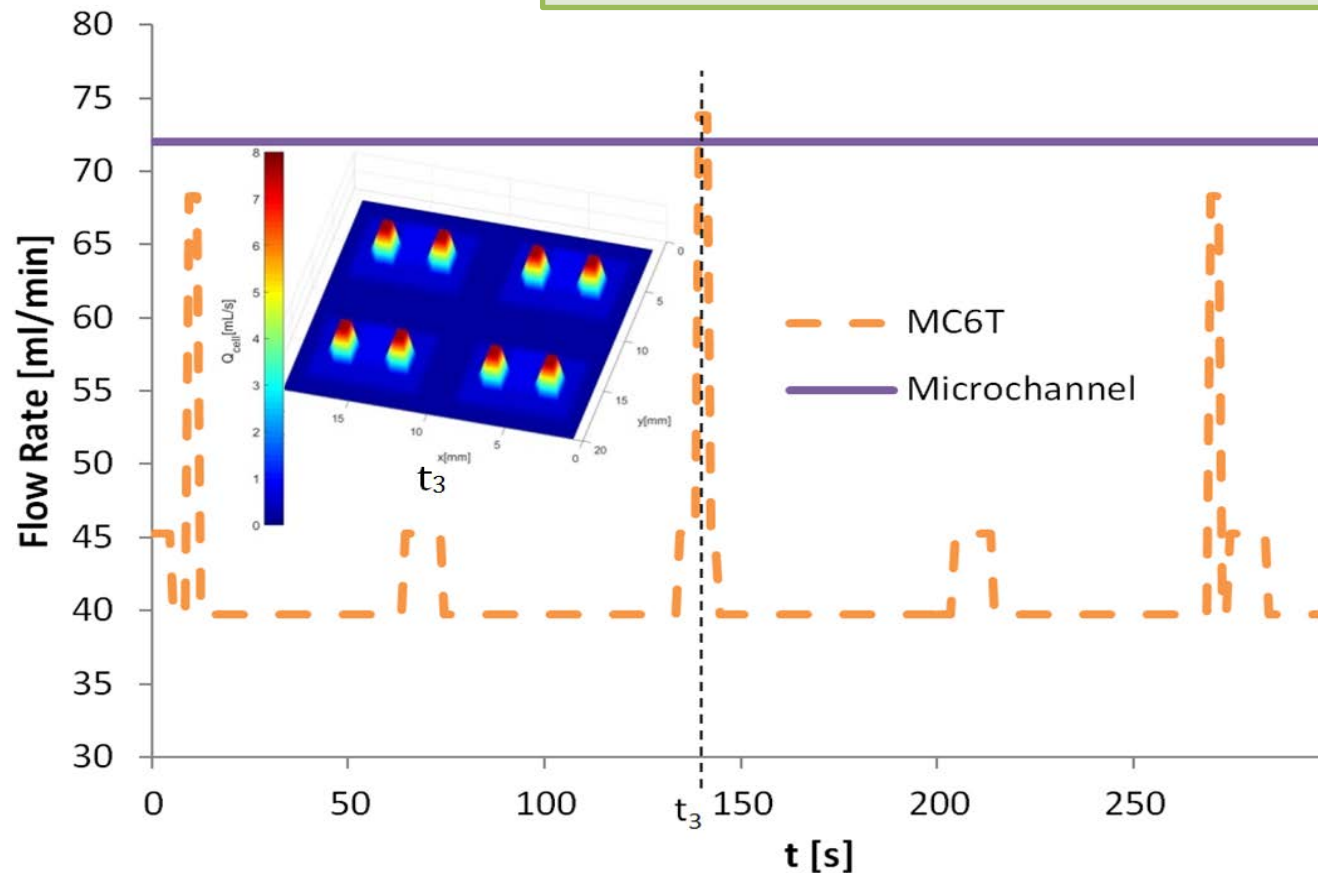
Temperature distribution on the microfluidic cell at chip surface (when submitted to 300 W/cm²).



Flow rate over time

In conventional microchannels

- High and constant flow rate (not tailored).

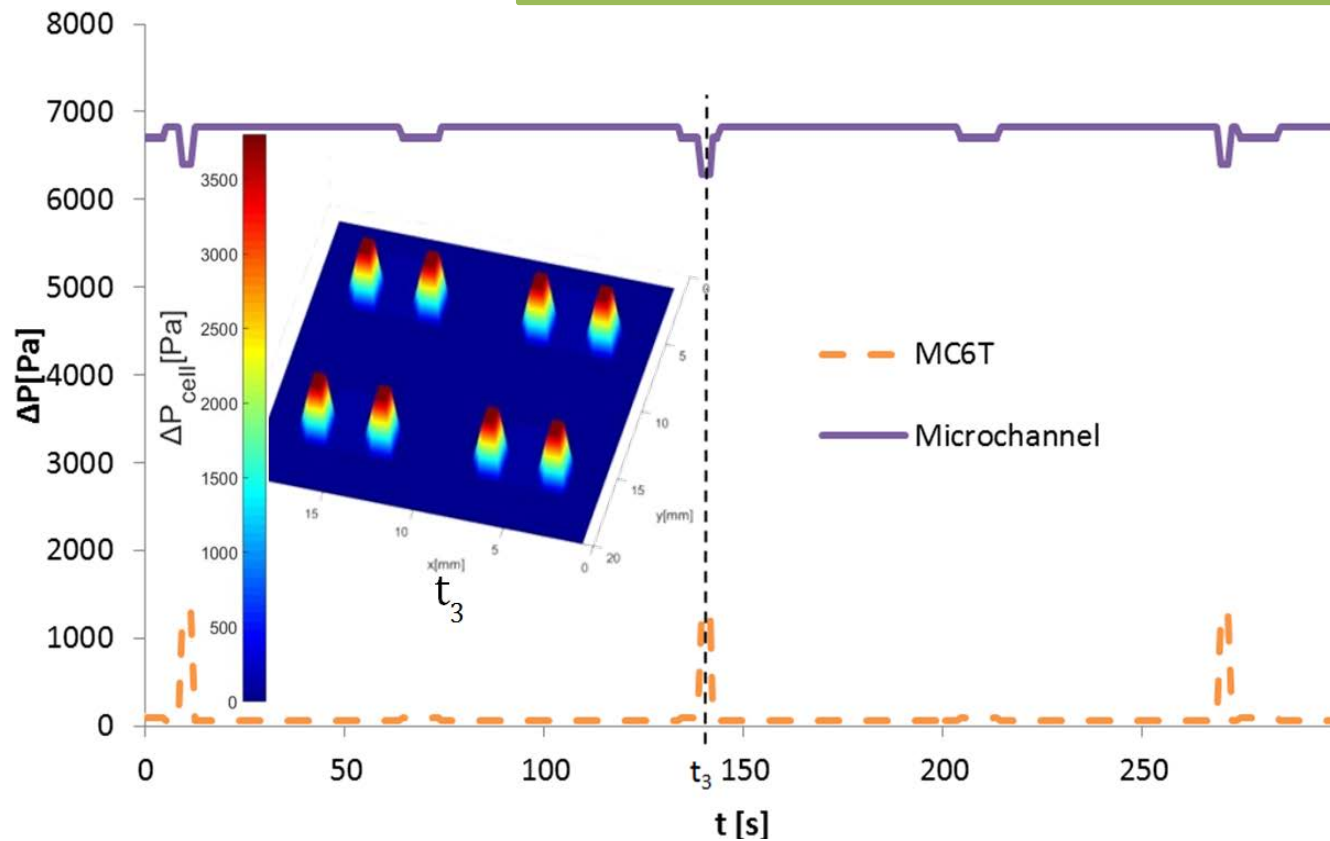




Pressure drop over time

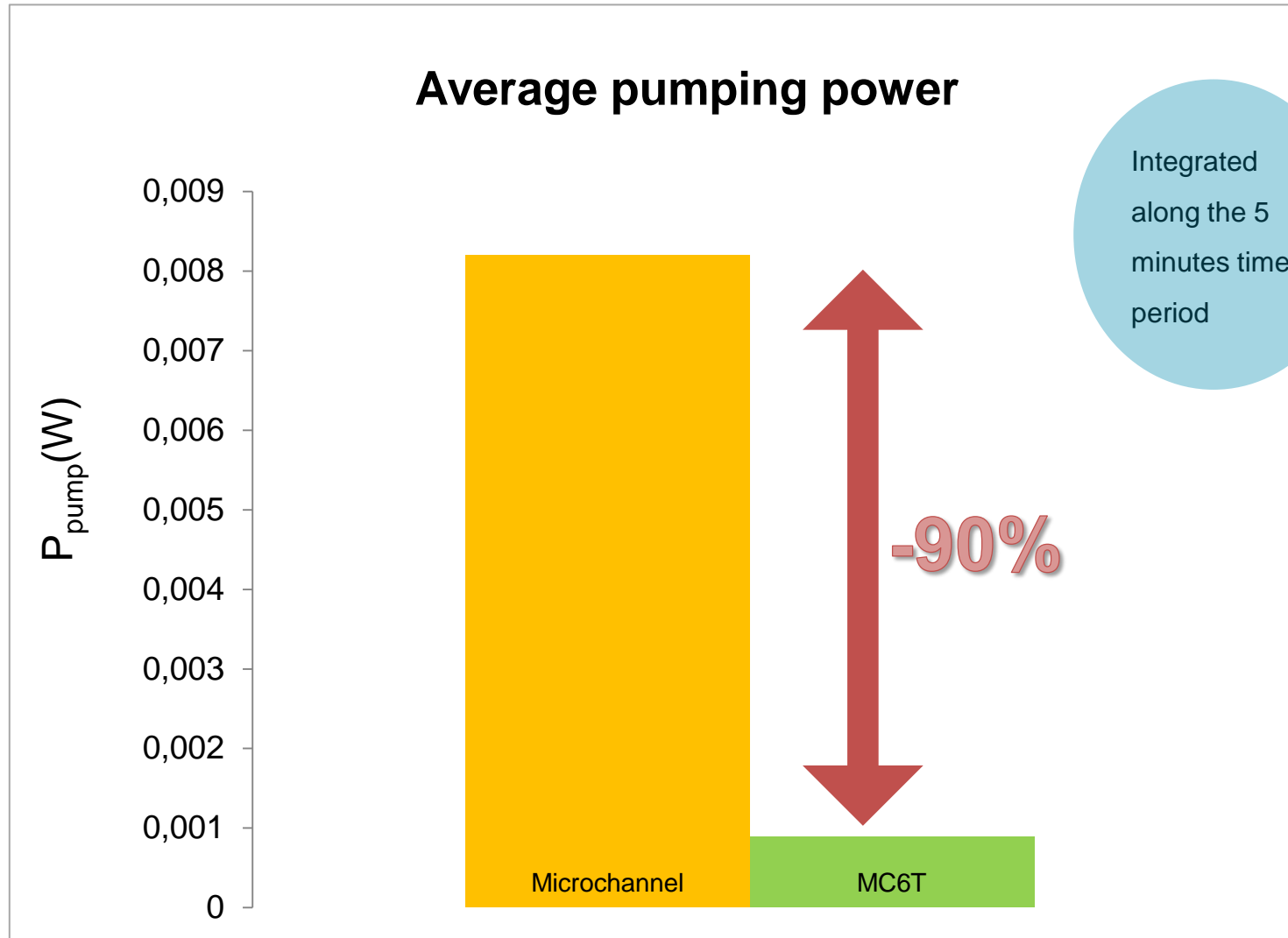
In conventional microchannels

- High pressure drops (larger lengths).



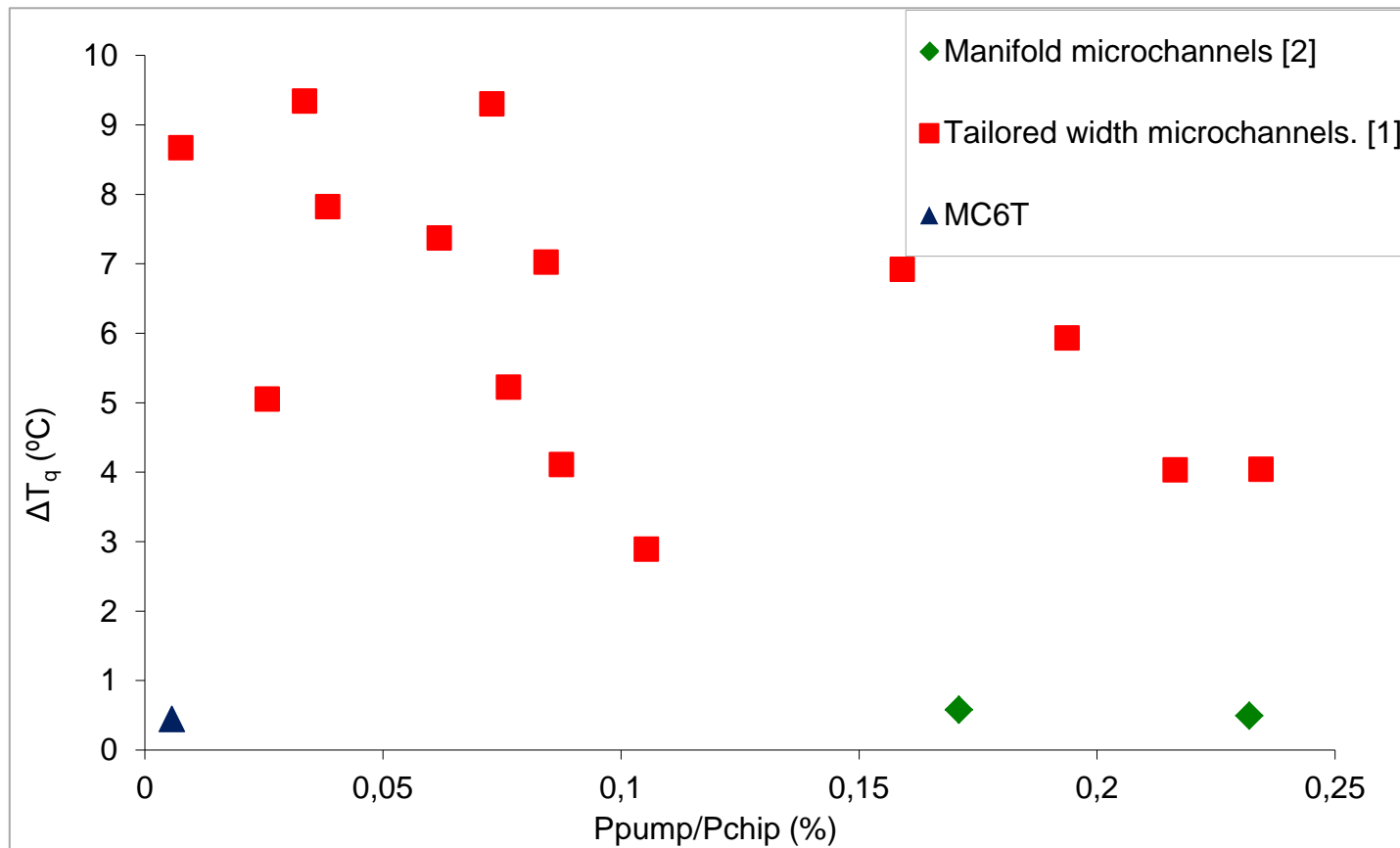


Efficiency improvement





Overall pumping performance



$$\Delta T_q = \frac{\Delta T_{chip,max}}{\left(\frac{q''_{hs}}{q''_{bg}}\right)}$$

[2]

[2] C. S. Sharma, M. K. Tiwari, S. Zimmermann, T. Brunswiler, G. Schlottig, B. Michel, and D. Poulikakos, "Energy efficient hotspot-targeted embedded liquid cooling of electronics," Appl. Energy, vol. 138, pp. 414–422, 2015.

[1] S. Riera, J. Barrau, M. Omri, L.G. Fréchet, J. Rosell, "Stepwise varying width microchannel cooling device for uniform wall temperature: experimental and numerical study", Applied Thermal Engineering, Volume 78, Pages 30-38, 2015.



Conclusions

Compared with conventional microchannel technology, the microfluidic cells matrix achieves:

- **89,2% of pumping power saved for a given heat load scenario.**
- Reduced **pressure drops** and **total coolant flow rates**.
- **Good temperature uniformity** even for **non-uniform and time dependent heat load scenarios**.



Acknowledgments

The research leading to these results has been performed within the **STREAMS project** (www.project-streams.eu) and received funding from the European Community's Horizon 2020 program under Grant Agreement n° 688564.*

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Thanks for your attention



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